

S.N.O.

	Description	Quantity
01	<p>3-D non-destructive X-ray system for inspection of soldered leadless Surface Mount Components (SMCs) including fine-pitch Land Grid Arrays (LGAs), Ball Grid Arrays (BGAs) etc. with standard accessories/equipment necessary for machine operation, spare parts, consumables, manuals (user, maintenance/service & operational), including on-site installation, commissioning and training.</p> <p>Make: SEC, Model: X-eye 5000</p> <p>Main Specifications:</p> <p>Focus: 5μm, Tube voltage: Max. 90kV, Tube current: Max. 0.25mA, Magnification: 6x to 120x, Image intensifier: 4/6 inch digital, X-ray CCD camera: 0.8M, Table size: 460 x 340mm, Axis X: 420mm, Axis Y: 300mm, Axis Z: 240mm, Tilt: +/- 45deg, Foot print: 1310 x 1060 x 1985mm, Power supply: AC 200-240V, 50 Hz, Leakage dose rate: 1μSy/h</p>	01 No.
2	<p>Laser cut stencil making machine for fabrication of stencils for solder paste printing with standard accessories/equipment necessary for machine operation, spare parts, consumables, manuals (user, maintenance/service & operational), including on-site installation, commissioning and training.</p> <p>Make: LPKF, Model: LPKF G 6080</p> <p>Main Specifications:</p> <p>Cutting area: 600 x 800mm Max frame size: 740 x 1800 x 40mm Max sheet size without frame: 650x850mm Thickness: 0.04mm(min) and 1mm(max) Cutting precision: +/- 2μm Repeatability: +/- 2μm Power supply: AC 200-240V, 50 Hz</p>	01 No.
3	<p>Multi zone reflow oven for reflow soldering of Surface Mount Devices (SMDs) with standard accessories/equipment necessary for machine operation, spare parts, consumables, manuals (user, maintenance/service & operational), including on-site installation, commissioning and training.</p> <p>Make: Samsung, Model: TRN I-e82M</p> <p>Main Features/Specifications:</p> <p>PC controlled compact design, temperature management by monitor display, error data storage, storage of Real Time Temperature check, efficient design for maintenance.</p> <p>Heating zone (cooling zone): 8 zones (2 zones), Heating zone length: 3840mm approx, cooling method: air cooling, PCB moving speed: 0.3-1.6m/min approx, PCB size: 50mm-350mm approx, PCB drop/stop prevention: photo sensor, voltage: 3-phase 220V and 50 Hz</p>	01 No.